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## Overvoltage Protector IC with Reverse Current Protection

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NO.EA-313-181010

### OUTLINE

The R5528Z001A is a CMOS-based overvoltage protector IC with reverse current protection that use an NMOS pass transistor to achieve ultra-low on resistance (Typ. 54mΩ). Overvoltage protection threshold is as high as 6.8V±3%. Also, continuous current capability is as high as 3A.

Internally, the R5528Z001A consists of a reverse current protection circuit, a soft-start circuit, a startup debounce circuit, an undervoltage lockout (UVLO) circuit, and a thermal shutdown circuit.

The R5528Z001A is offered in a small and thin WLCSP-9-P1 package which achieves the smallest possible footprint solution on boards where area is limited.

### FEATURES

- Input Voltage Range ( $V_{IN}$ ) ..... 2.3V to 36V
- Output Current ( $I_{OUT}$ ) ..... Max. DC 3A
- Switch On Resistance ( $R_{ON}$ ) ..... 54mΩ ( $V_{IN} = 5.0V, I_{OUT} = 100mA$ )
- OVP Threshold Accuracy ..... 6.8V±3%
- PG Function
- Reverse Current Protection Circuit
- Soft-start Circuit
- Startup Debounce Circuit ..... 15ms
- Thermal Shutdown Circuit
- Package ..... WLCSP-9-P1 ( 1.27 mm x 1.27 mm x 0.64 mm )

### APPLICATIONS

- Smartphones, Tablet PCs
- Portable devices

**BLOCK DIAGRAMS**

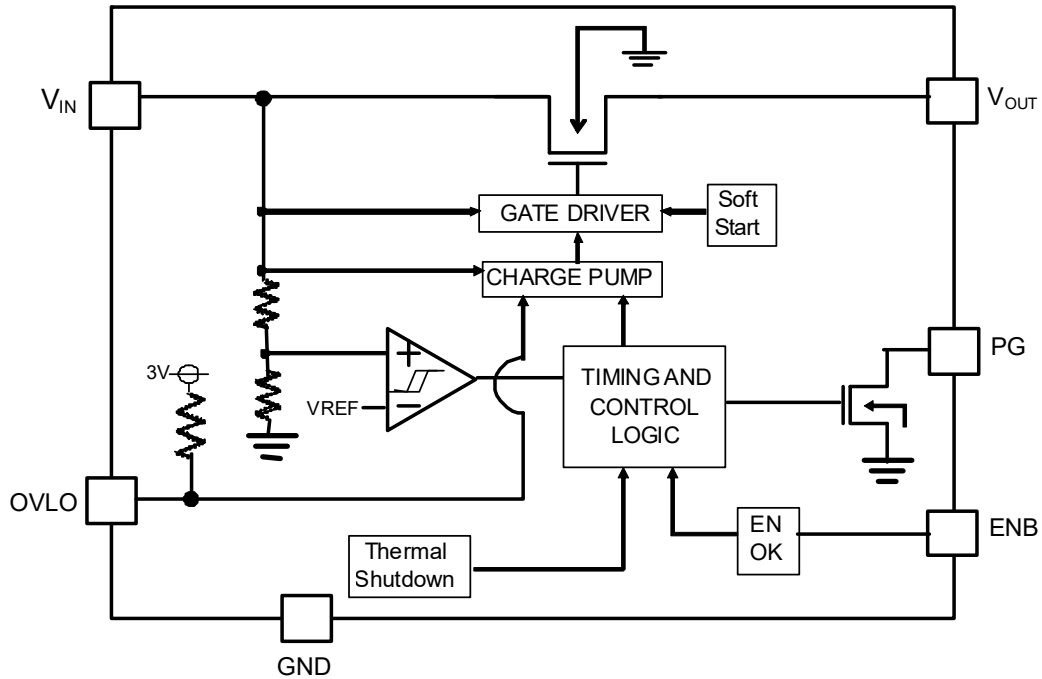


Figure 1. R5528Z001A

**SELECTION GUIDE**

| Product Name    | Package    | Quantity per Reel | Pb Free | Halogen Free |
|-----------------|------------|-------------------|---------|--------------|
| R5528Z001A-E2-F | WLCSP-9-P1 | 5,000pcs          | Yes     | Yes          |

**PIN CONFIGURATIONS**

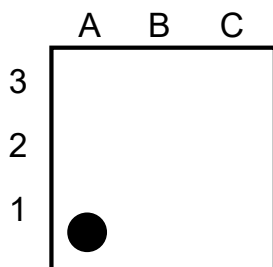


Figure 2. Top View

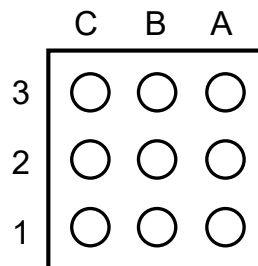


Figure 3. Bottom View

## PIN DESCRIPTION

| Pin No. | Symbol    | Pin Description  |
|---------|-----------|--|
| A1      | PG        | Open Drain Flag Output Pin<br>PG is driven low after input voltage is stable between minimum $V_{IN}$ and $V_{IN-OVLO}$ after debounce (delay).  |
| A2      | OVLO      | Overtoltage Lockout Input Pin<br>Applying a voltage less than OVLO threshold ( $V_{OVLO\_TH}$ ) to the overvoltage lockout input pin can turn off a switch.<br>When the overvoltage lockout input pin is Open, it outputs an OVLO open voltage ( $V_{OVLO\_OP}$ ). |
| A3      | ENB       | Active-Low ENB Input Pin   |
| B1, C1  | $V_{IN}$  | Input Pin  |
| B2      | I.C       | Internally Connected to Ground<br>Unconnected or connected to GND  |
| B3, C3  | $V_{OUT}$ | Output Pin   |
| C2      | GND       | Ground Pin   |

## ABSOLUTE MAXIMUM RATINGS

| Symbol     | Item  | Rating      | Unit |
|------------|---|-------------|------|
| $V_{IN}$   | Input Voltage                                   | -0.3 to 40  | V    |
| $V_{OUT}$  | Output Voltage                                  | -0.3 to 8.0 | V    |
| $V_{ENB}$  | ENB Pin Input Voltage                           | -0.3 to 6.5 | V    |
| $V_{PG}$   | PG Pin Voltage                                  | -0.3 to 6.5 | V    |
| $V_{OVLO}$ | OVLO Pin Input Voltage                          | -0.3 to 6.5 | V    |
| $I_{PG}$   | PG Pin Current                                  | 14          | mA   |
| $I_{OUT}$  | Output Current                                  | 3.0         | A    |
| $P_D$      | Power Dissipation (High Wattage Land Pattern)*1 | 1190        | mW   |
| $T_{opt}$  | Operating Temperature Range                     | -40 to +85  | °C   |
| $T_{stg}$  | Storage Temperature                             | -55 to +125 | °C   |

\*1 Refer to *POWER DISSIPATION* for detailed information.

### ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause the permanent damages and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings is not assured.

### RECOMMENDED OPERATING CONDITIONS (ELECTRICAL CHARACTERISTICS)

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if when they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

## ELECTRICAL CHARACTERISTICS

$V_{IN} = 2.3V$  to  $36V$ ,  $I_{OUT} = 1mA$ ,  $C_{IN} = 1\mu F$ ,  $C_{OUT} = 1\mu F$ , unless otherwise noted. Typical values are  $V_{IN} = 5V$  and  $T_a = 25^\circ C$ .  
The specifications surrounded by   are guaranteed by Design Engineering at  $-40^\circ C \leq T_a \leq 85^\circ C$ .

(Ta=25°C)

| Symbol         | Item                             | Conditions   | Min.  | Typ. | Max.   | Unit       |
|----------------|----------------------------------|--|---|------|--|------------|
| $V_{IN}$       | Input Voltage                    |  | <span style="border: 1px solid black; padding: 0 2px;">2.3</span> |      | <span style="border: 1px solid black; padding: 0 2px;">36</span>   | V          |
| $I_{IN}$       | Input Supply Current             | $V_{ENB} = 0V$ , $V_{IN} = 5V$ , $I_{OUT} = 0mA$   |   | 50   | <span style="border: 1px solid black; padding: 0 2px;">120</span>  | $\mu A$    |
| $I_{IN\_DIS}$  | Input Disable Current            | $V_{ENB} = 0V$ , $V_{IN} = 5V$ , $V_{OVLO} = 0V$   |   | 40   | <span style="border: 1px solid black; padding: 0 2px;">120</span>  | $\mu A$    |
| $I_{IN\_Q}$    | Input Shutdown Current           | $V_{ENB} = 5V$ , $V_{IN} = 5V$ , $V_{OUT} = 0V$  |   | 1.0  | <span style="border: 1px solid black; padding: 0 2px;">12</span>   | $\mu A$    |
| $I_{OUT\_DIS}$ | Output Disable Current           | $V_{ENB} = 0V$ , $V_{OUT} = 5V$ , $V_{IN} = 5V$ ,<br>$V_{OVLO} < V_{OVLO\_TH}$   |   |      | <span style="border: 1px solid black; padding: 0 2px;">3</span>    | $\mu A$    |
|                |                                  | $V_{ENB} = 0V$ , $V_{OUT} = 5V$ , $V_{IN} > V_{IN\_OVLO}$  |   |      |  |            |
| $I_{OUT\_SD}$  | Output Shutdown Current          | $V_{ENB} = 5V$ , $V_{OUT} = 5V$ , $V_{IN} = 5V$  |   |      | <span style="border: 1px solid black; padding: 0 2px;">5.5</span>  | $\mu A$    |
| $R_{ON}$       | On Resistance                    | $V_{IN} = 5V$ , $I_{OUT} = 100mA$  |   | 54   | <span style="border: 1px solid black; padding: 0 2px;">100</span>  | m $\Omega$ |
| $V_{IN\_OVLO}$ | Overvoltage Protection Threshold | $V_{IN}$ rising  | <span style="border: 1px solid black; padding: 0 2px;">6.6</span> | 6.8  | <span style="border: 1px solid black; padding: 0 2px;">7.0</span>  | V          |
|                |                                  | $V_{IN}$ falling   | <span style="border: 1px solid black; padding: 0 2px;">6.4</span> |      |  | V          |
| $C_{OUT}$      | OUT Load Capacitance             |  |   |      | <span style="border: 1px solid black; padding: 0 2px;">1000</span> | $\mu F$    |
| $V_{OVLO\_OP}$ | OVLO Open voltage                | $V_{ENB} = 0V$ , $V_{IN} = 5.0V$   |   | 3.0  | <span style="border: 1px solid black; padding: 0 2px;">3.6</span>  | V          |
| $R_{OVLO\_PU}$ | OVLO Pull-up Resistance          |  |   | 500  |  | k $\Omega$ |
| $V_{OVLO\_TH}$ | OVLO Force Off Voltage           |  | <span style="border: 1px solid black; padding: 0 2px;">0.6</span> | 1.0  | <span style="border: 1px solid black; padding: 0 2px;">1.4</span>  | V          |
| $V_{IH}$       | ENB Input High Voltage           |  | <span style="border: 1px solid black; padding: 0 2px;">1.4</span> |      |  | V          |
| $V_{IL}$       | ENB Input Low Voltage            |  |   |      | <span style="border: 1px solid black; padding: 0 2px;">0.4</span>  | V          |
| $I_{ENB}$      | ENB Input Leakage                |  | <span style="border: 1px solid black; padding: 0 2px;">-1</span>  |      | <span style="border: 1px solid black; padding: 0 2px;">1</span>    | $\mu A$    |
| $V_{OL}$       | PG Output Low Voltage            | $I_{SINK} = 1mA$   |   |      | <span style="border: 1px solid black; padding: 0 2px;">0.4</span>  | V          |
| $V_{PG\_LEAK}$ | PG Leakage Current               | $V_{IO} = 3.3V^{*2}$   | <span style="border: 1px solid black; padding: 0 2px;">-1</span>  |      | <span style="border: 1px solid black; padding: 0 2px;">1</span>    | $\mu A$    |
| $t_{DEB}$      | IN Debounce Time                 | starts when $2.3V < V_{IN}(5V) < V_{IN\_OVLO}$ and ends when charge-pump is turned on <sup>*3</sup>  | <span style="border: 1px solid black; padding: 0 2px;">10</span>  | 15   | <span style="border: 1px solid black; padding: 0 2px;">35</span>   | ms         |
| $t_{SS}$       | Soft-start Time                  | starts when $2.3V < V_{IN} < V_{IN\_OVLO}$ and ends when $V_{OUT} = 90\%$ of $V_{IN}$  |   | 30   |  | ms         |
| $t_{ON}$       | Turn-on Time During Soft-start   | $V_{IN} = 5V$ , $R_L = 50\Omega$ , $C_L = 10\mu F$ , starts when $V_{OUT} = 20\%$ of $V_{IN}$ and ends when $V_{OUT} = 80\%$ of $V_{IN}$ <sup>*3</sup> | <span style="border: 1px solid black; padding: 0 2px;">1.5</span> | -    |  | ms         |
| $t_{OFF}$      | Turn-off Time                    | $R_L = 50\Omega$ , starts when $V_{IN} > V_{IN\_OVLO}$ (2V/ $\mu s$ ) and ends when $V_{OUT} = 80\%$ of $V_{IN}$                                       |   | 1.5  |  | $\mu s$    |
|                |                                  | starts when $V_{ENB}$ is switched from "L" to "H", ends when $V_{OUT} = 80\%$ of $V_{IN}$ , $R_L = 50\Omega$   |   | 84   |  |            |
| $T_{SHDN}$     | Thermal Shut Down                |  |   | 150  |  | $^\circ C$ |
| $T_{HYST}$     | Thermal Hysteresis               |  |   | 20   |  | $^\circ C$ |
| $V_{UVREL}$    | UVLO Release Voltage             | $V_{IN}$ rising  |   | 2.05 | <span style="border: 1px solid black; padding: 0 2px;">2.3</span>  | V          |
| $V_{UVHYS}$    | UVLO Hysteresis                  | $V_{IN}$ falling   |   | 0.15 |  | V          |

All test items listed under *ELECTRICAL CHARACTERISTICS* are done under the pulse load condition ( $T_j \approx T_a = 25^\circ C$ ) except Soft-Start Time and Turn-off Time and UVLO Hysteresis.

<sup>\*2</sup> Refer to *TYPICAL APPLICATION AND TECHNICAL NOTES*.

<sup>\*3</sup> Refer to *TIMING CHART*.

## TIMING CHART

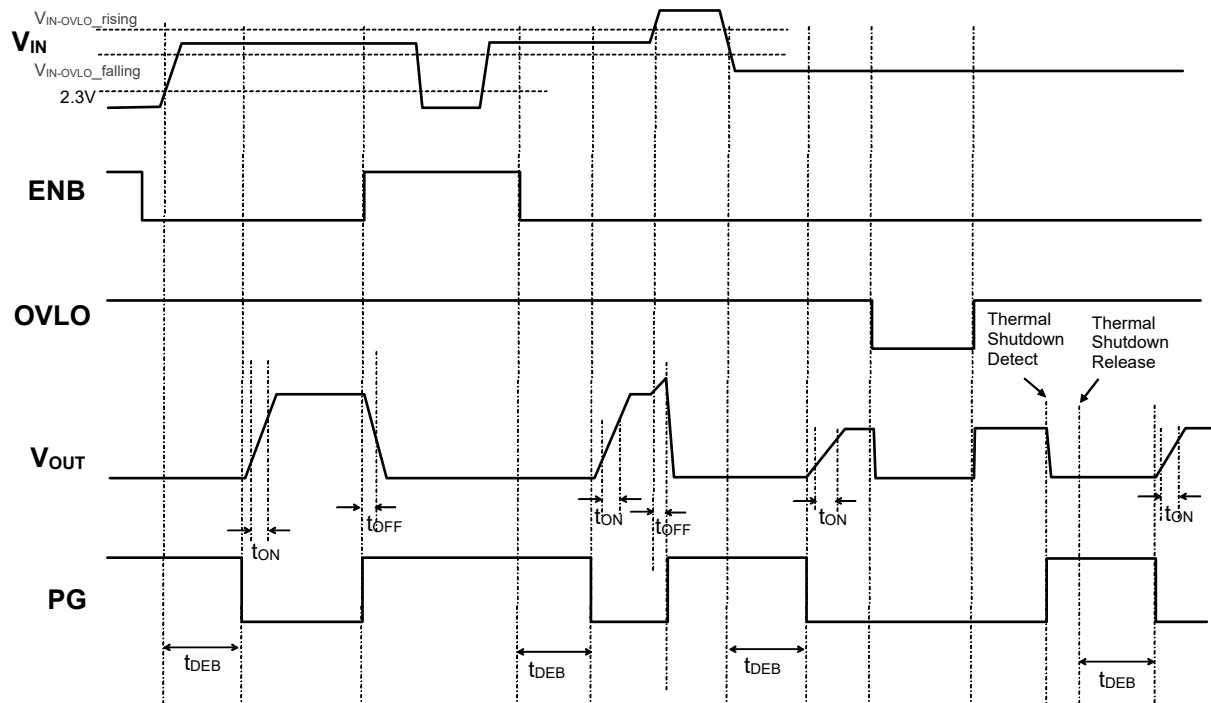


Figure 4. Timing Chart

## TYPICAL APPLICATIONS AND TECHNICAL NOTES

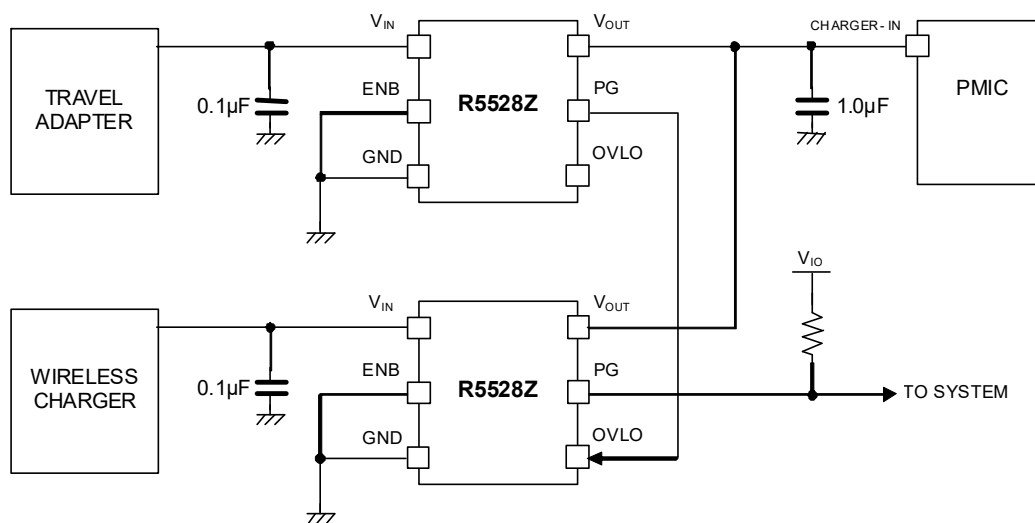


Figure 5. Typical Applications

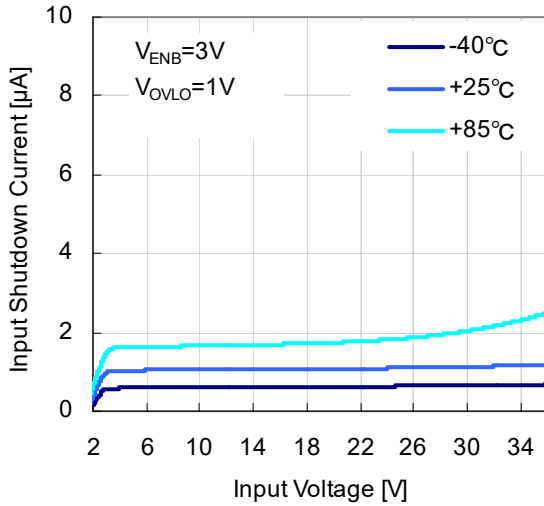
### Technical Notes

The R5528Z001A does not require any bypass capacitor between  $V_{IN}$  and GND. However, connecting a  $0.1\mu\text{F}$  or more capacitor between  $V_{IN}$  and GND may improve the performance against the noise.

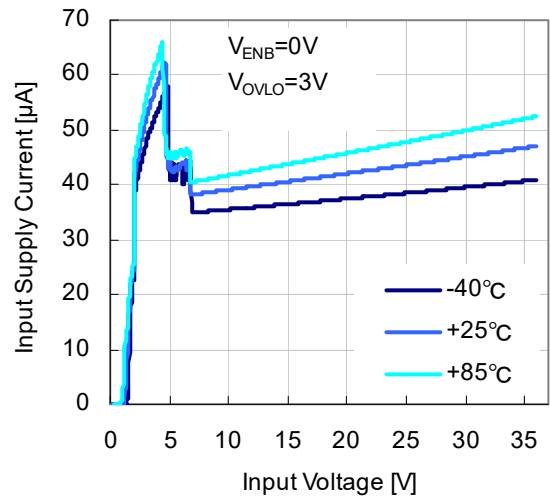
If there's any possibility of generating spike noise due to the parasitic element (inductance) of  $V_{IN}$ , connect an appropriate-sized capacitor between  $V_{IN}$  and GND.

## TYPICAL CHARACTERISTIC

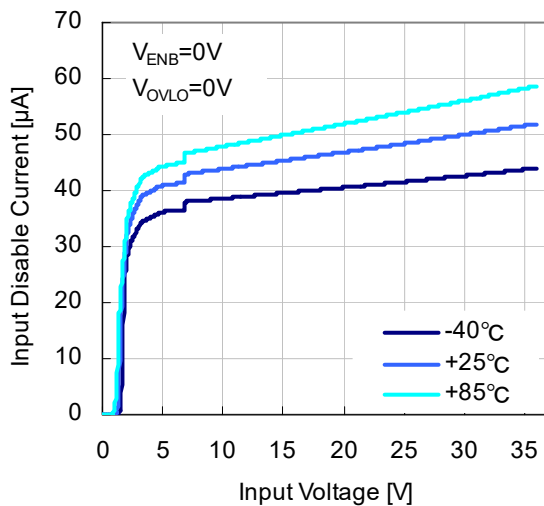
1) Input Shutdown Current VS. Input Voltage  
R5528Z001A



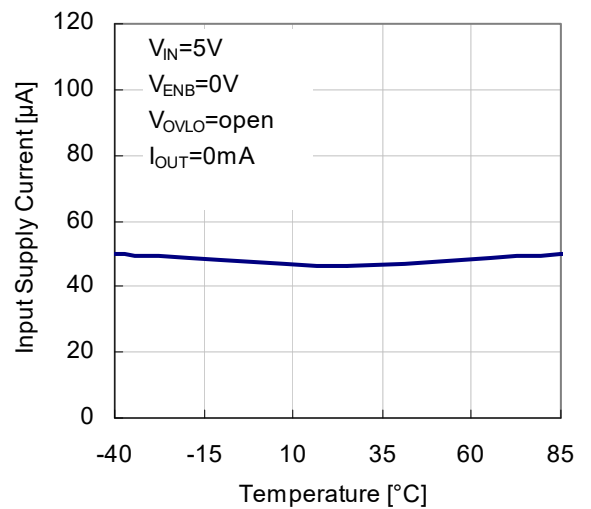
2) Input Supply Current VS. Input Voltage  
R5528Z001A



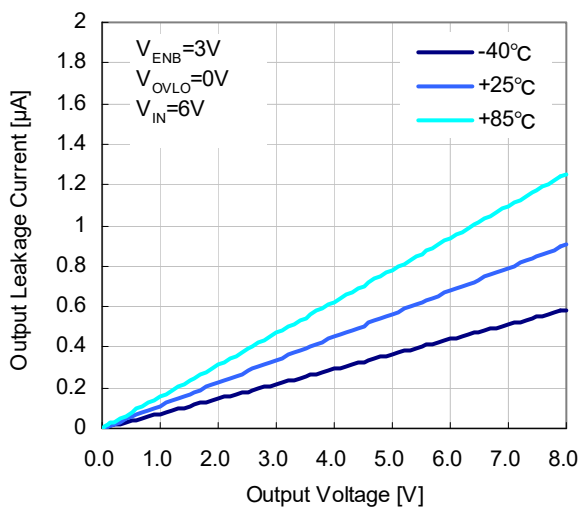
3) Input Disable Current VS. Input Voltage  
R5528Z001A



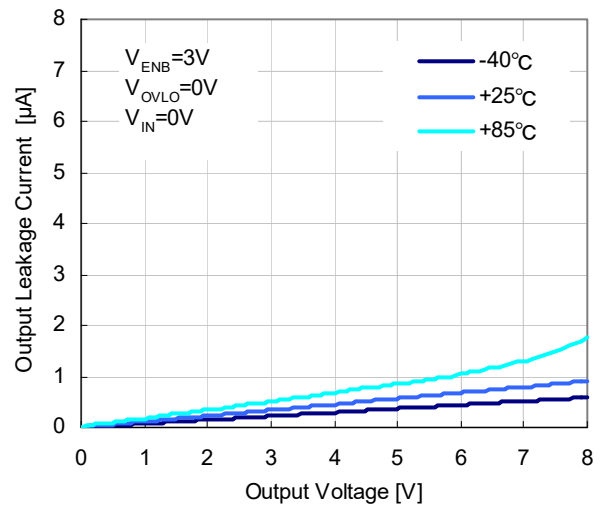
4) Input Supply Current VS. Temperature  
R5528Z001A



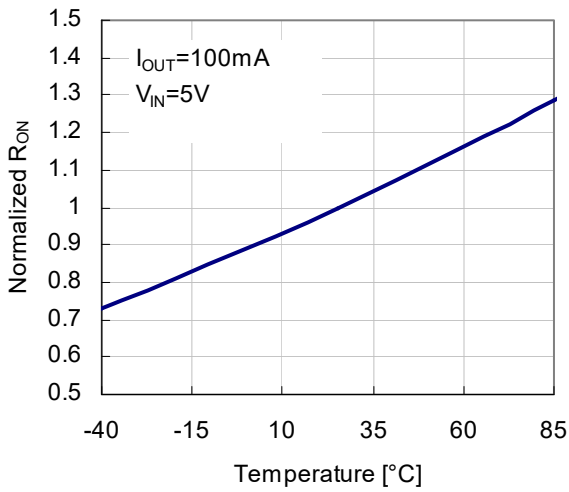
5) Output Leakage Current (6V) VS. Output Voltage  
R5528Z001A



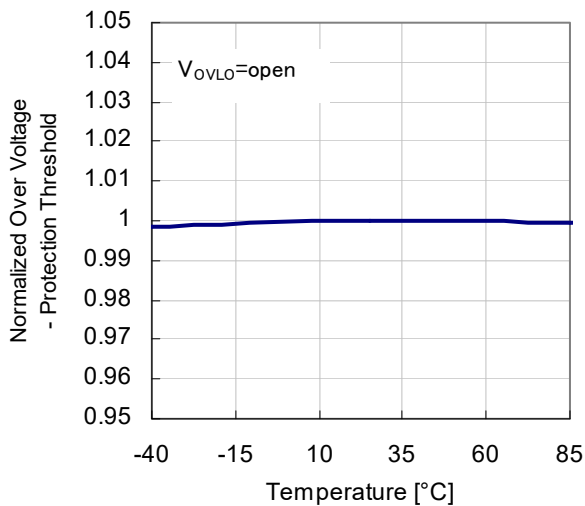
6) Output Leakage Current (0V) VS. Output Voltage  
R5528Z001A



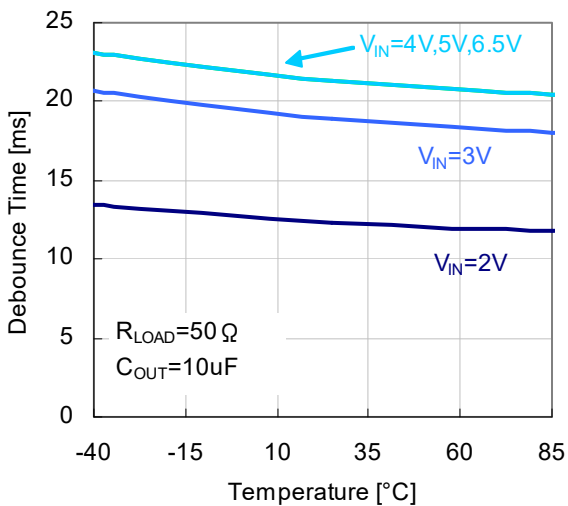
**7) Normalized On-Resistance VS. Temperature**  
**R5528Z001A**



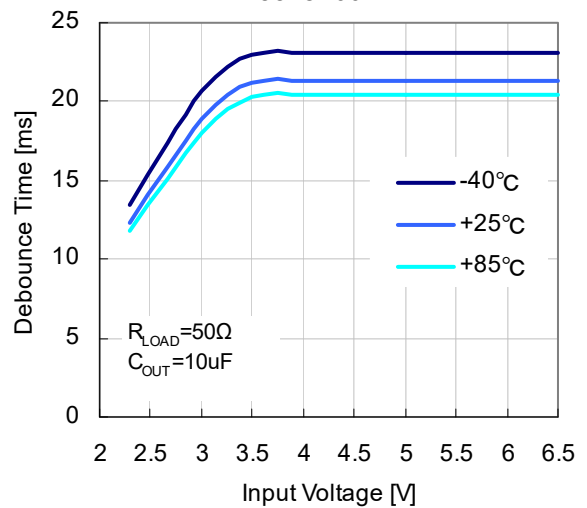
**8) Normalized Overvoltage Protection Threshold ( IN rising ) VS. Temperature**  
**R5528Z001A**



**9) Debounce Time VS. Temperature**  
**R5528Z001A**

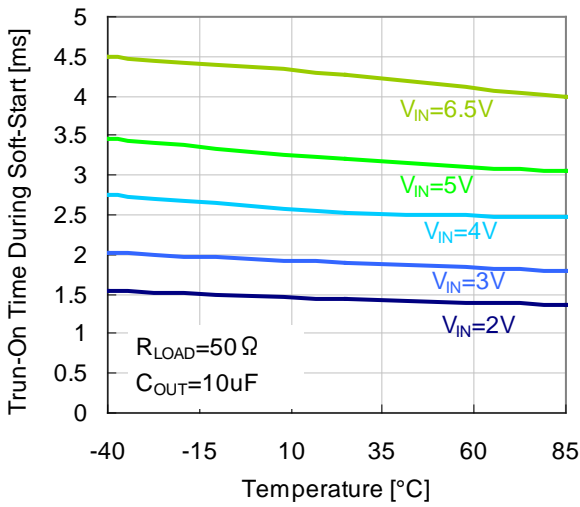


**10) Debounce Time VS. Input Voltage**  
**R5528Z001A**





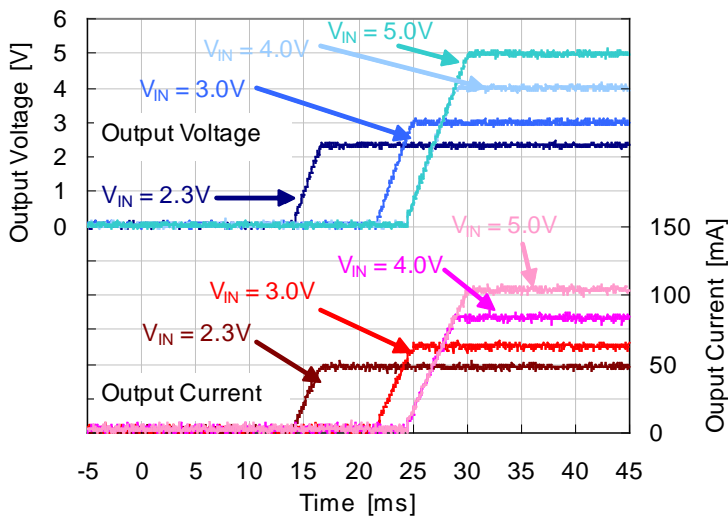
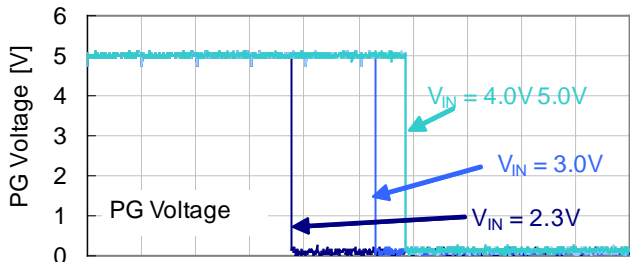
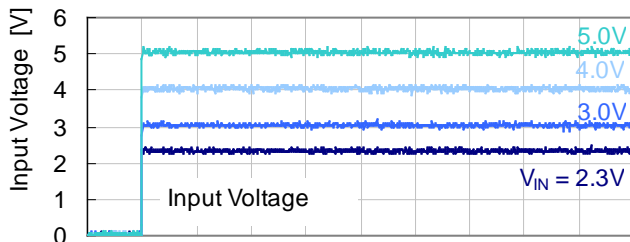
11) Trun-On Time VS. Temperature  
R5528Z001A



12) Power-Up Response (V<sub>IN</sub> = 2.3V/ 3.0V/ 4.0V/ 5.0V)

R5528Z001A

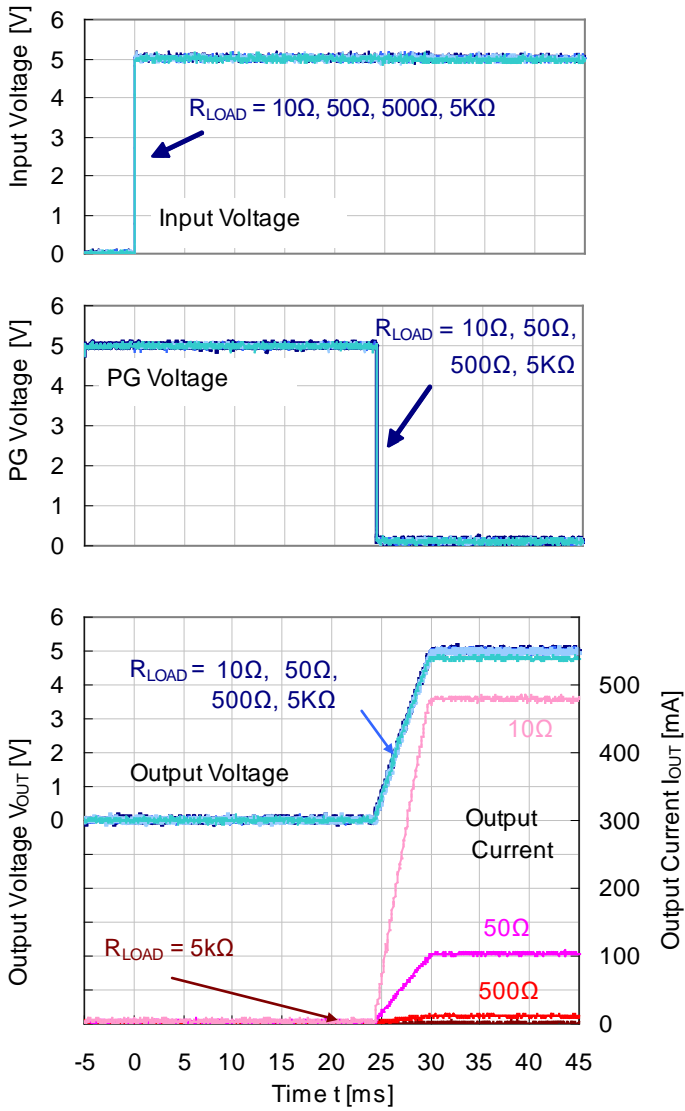
R<sub>LOAD</sub>=50Ω/C<sub>OUT</sub>=10μF/P<sub>G</sub>=10KΩ to 5V/V<sub>ENB</sub>=0V/T<sub>a</sub>=25°C



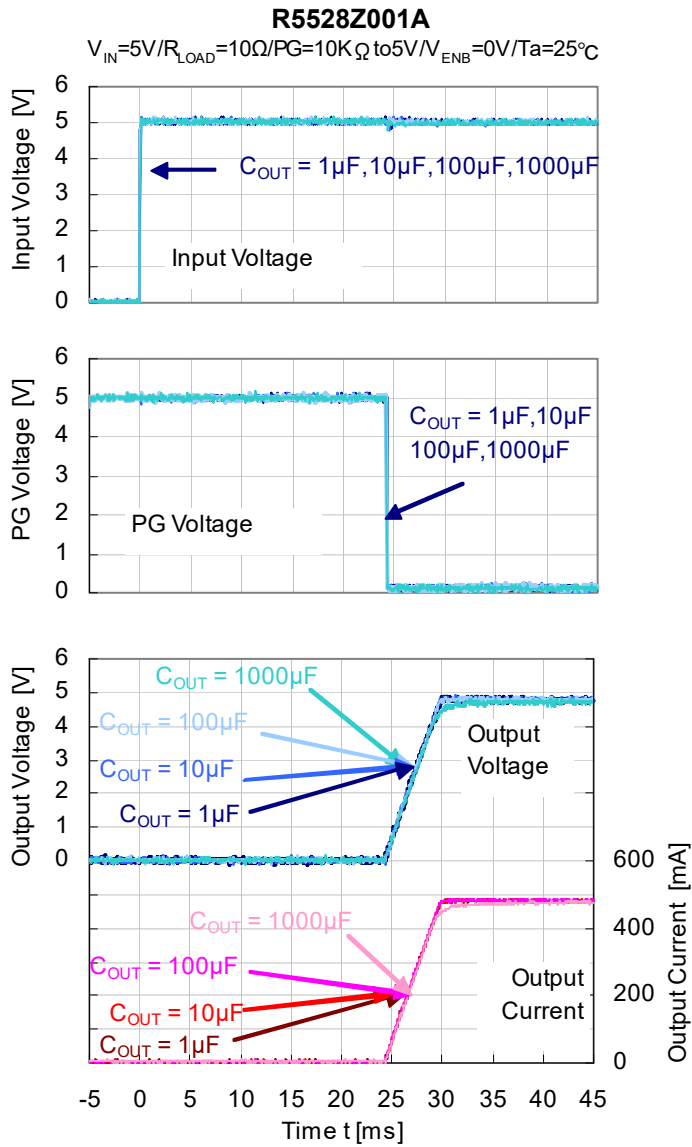
13) Power-Up Response ( $R_{LOAD} = 10\Omega / 50\Omega / 500\Omega / 5K\Omega$ )

R5528Z001A

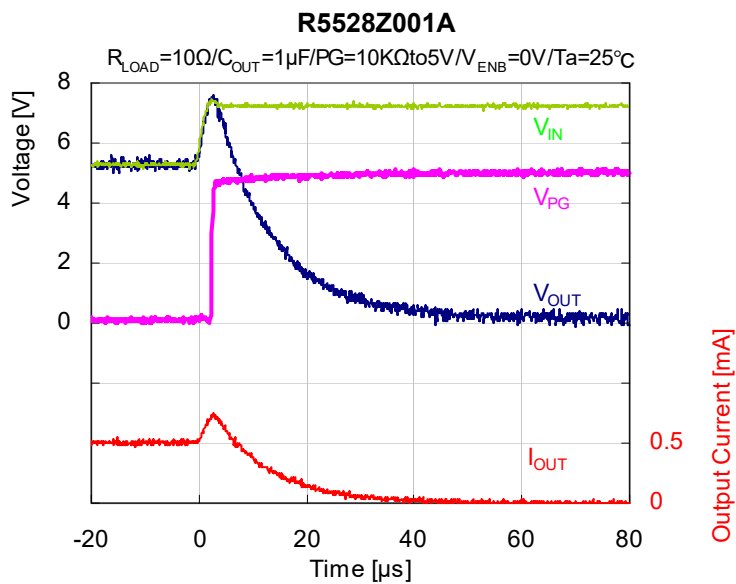
$V_{IN}=5.0V / C_{OUT}=10\mu F / PG=10K\Omega \text{ to } 5V / V_{ENB}=0V / T_a=25^\circ C$



14) Power-Up Response ( $C_{OUT} = 1\mu\text{F}/ 10\mu\text{F}/ 100\mu\text{F}/ 1000\mu\text{F}$ )



15) Overvoltage Fault Response



The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following conditions are used in this measurement.

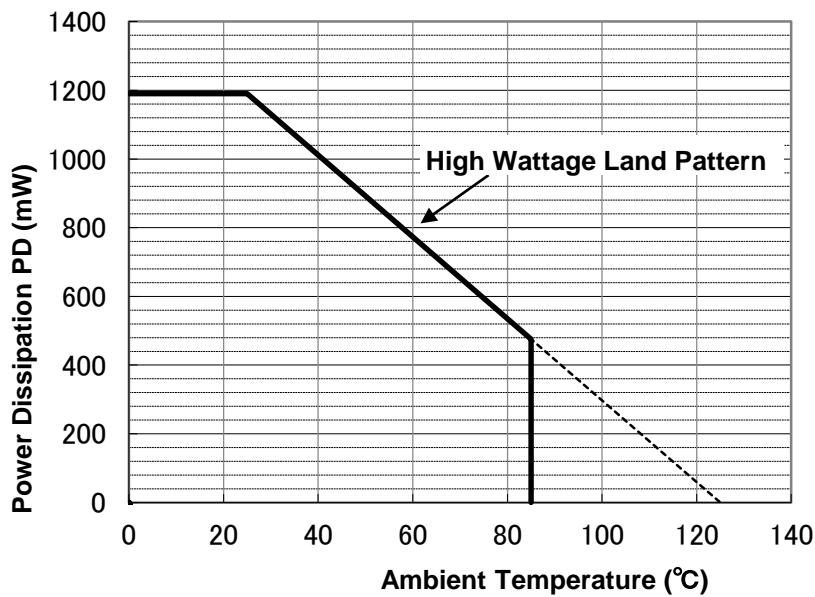
**Measurement Conditions**

| <b>High Wattage Land Pattern</b> |   |
|----------------------------------|---|
| Environment                      | Mounting on Board (Wind Velocity = 0 m/s)   |
| Board Material                   | Glass Cloth Epoxy Plastic (Four-layers)   |
| Board Dimensions                 | 76.2 mm × 114.3 mm × 1.6 mm   |
| Copper Ratio                     | Outer Layers (First and Fourth Layers): Approx. 60%<br>Inner Layers (Second and Third Layers): 100% |

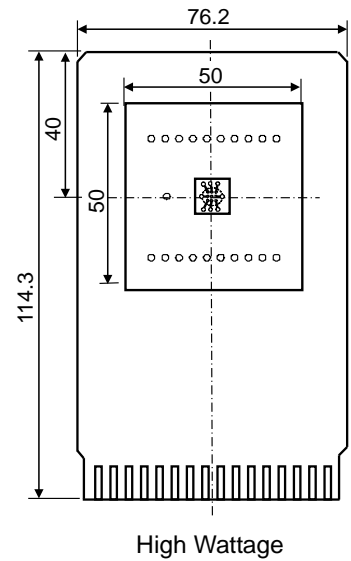
**Measurement Result**

(Ta = 25°C, Tjmax = 125°C)

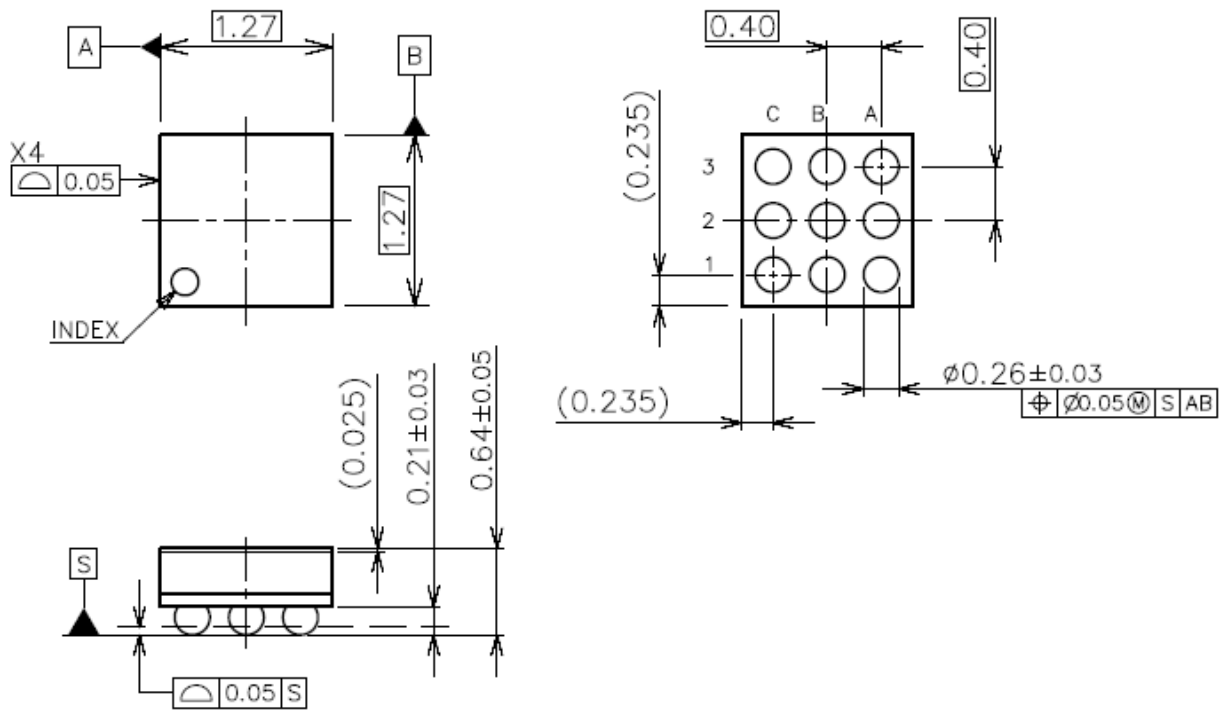
| <b>High Wattage Land Pattern</b> |  |
|----------------------------------|--|
| Power Dissipation                | 1190 mW  |
| Thermal Resistance               | $\theta_{ja} = (125 - 25^\circ\text{C}) / 1.19 \text{ W} = 84^\circ\text{C/W}$ |



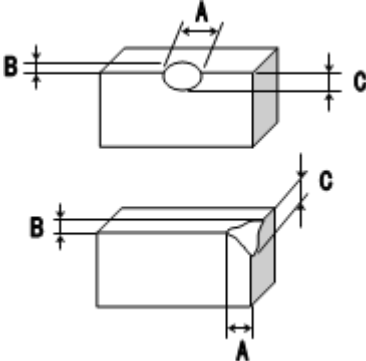
**Power Dissipation vs. Ambient Temperature**



**Measurement Board Pattern**  
 ○ IC Mount Area (mm)



WLCSP-9-P1 Package Dimensions (Unit: mm)

| No. | Inspection Items             | Inspection Criteria   | Figure  |
|-----|------------------------------|---|---|
| 1   | Package chipping             | <p><math>A \geq 0.2\text{mm}</math> is rejected<br/> <math>B \geq 0.2\text{mm}</math> is rejected<br/> <math>C \geq 0.2\text{mm}</math> is rejected<br/>                     And, Package chipping to Si surface and to bump is rejected.</p>                                   |  |
| 2   | Si surface chipping          | <p><math>A \geq 0.2\text{mm}</math> is rejected<br/> <math>B \geq 0.2\text{mm}</math> is rejected<br/> <math>C \geq 0.2\text{mm}</math> is rejected<br/>                     But, even if <math>A \geq 0.2\text{mm}</math>, <math>B \leq 0.1\text{mm}</math> is acceptable.</p> |   |
| 3   | No bump                      | No bump is rejected.  |   |
| 4   | Marking miss                 | To reject incorrect marking, such as another product name marking or another lot No. marking.   |   |
| 5   | No marking                   | To reject no marking on the package.  |   |
| 6   | Reverse direction of marking | To reject reverse direction of marking character.   |   |
| 7   | Defective marking            | To reject unreadable marking. (Microscope: X15/ White LED/ Viewed from vertical direction)  |   |
| 8   | Scratch                      | To reject unreadable marking character by scratch. (Microscope: X15/ White LED/ Viewed from vertical direction)   |   |
| 9   | Stain and Foreign material   | To reject unreadable marking character by stain and foreign material. (Microscope: X15/ White LED/ Viewed from vertical direction)  |   |



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